

NOVASTACK® 35-HDN

5G mmWave 안테나 모듈, 5G 기기에 최적, 풀 실드 공간, 절약형 디자인, 콜슨 합금을 사용한 단자에 의한 전원 공급 가능, 0.35 mm Pitch, 결합 높이 0.7 mm

Product Specifications:

Board Pitch (mm)		0.35
Wiping Length (mm)		0.14
Mated Size (mm)	Height	0.7 +/- 0.05
	Width	Formula: 4.15 (10 P), 5.90 (20 P), 7.90 (30 P)
	Depth	2.15 mm
Frequency		DC ~ 15 GHz
Current Rating	Signal	1.0 A / pin (Max. 10 P) (12 P and over : 12.0 A AC/DC (Total))
	Power	-
Pin Counts	Range	10 - 60
	Available	10, 20, 30

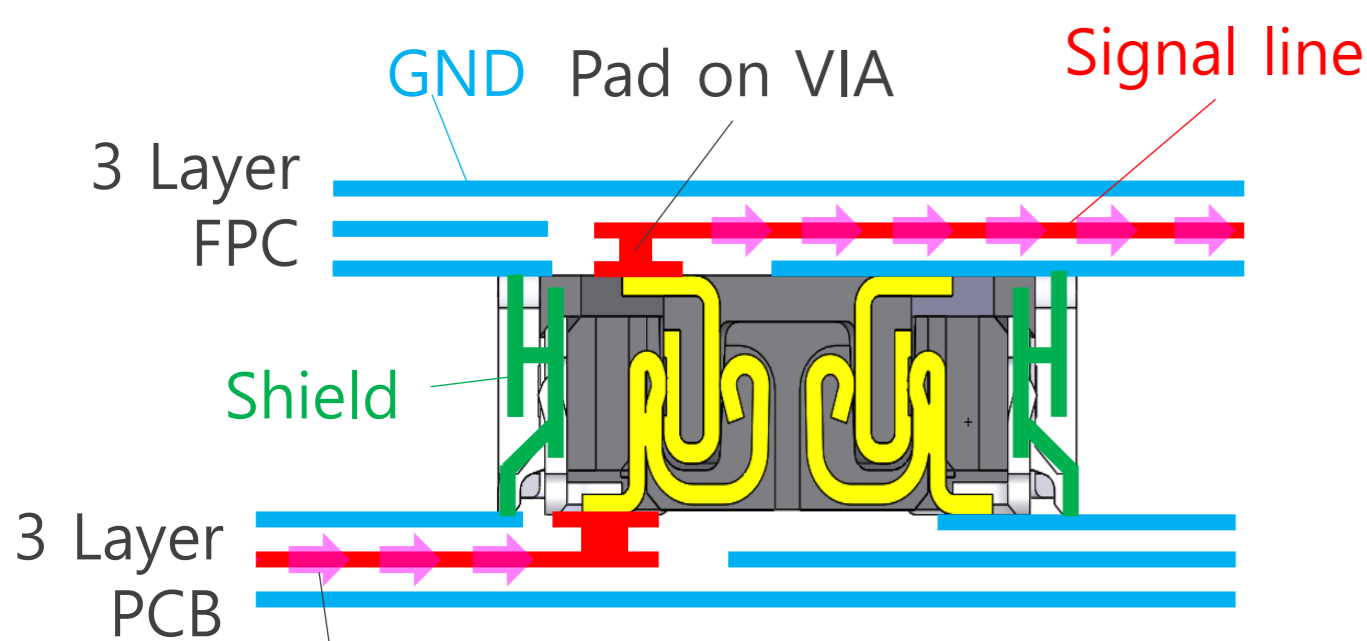
Applicable Standards (Reference Only):

USB4 (20 Gbps/lane) USB 3.1 Gen 2 (10 Gbps)

*기재가 되어있지 않은 핀 수의 대응 여부에 대해서는 문의해 부탁드립니다.

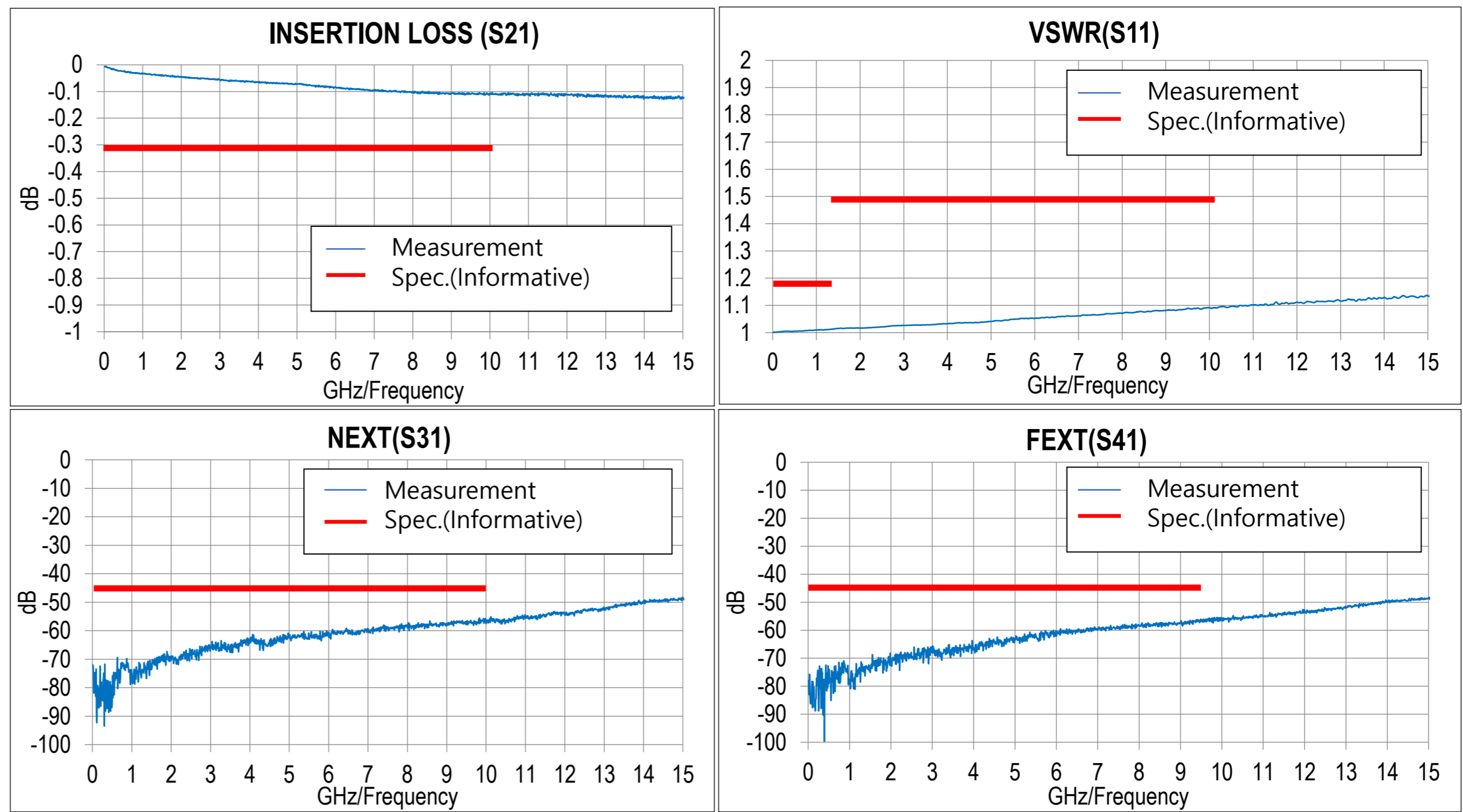
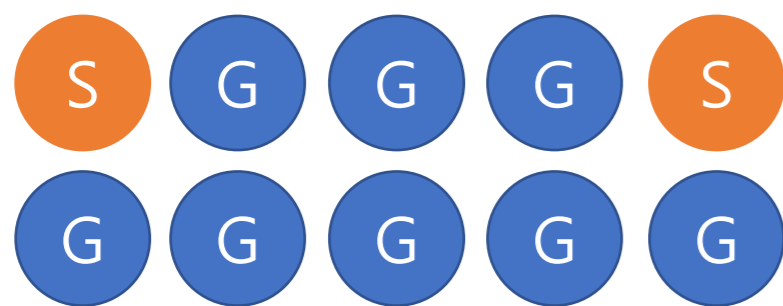


▶ 고주파 Application에 최적 (5G mmWave, USB4 / Thunderbolt 4, etc.)



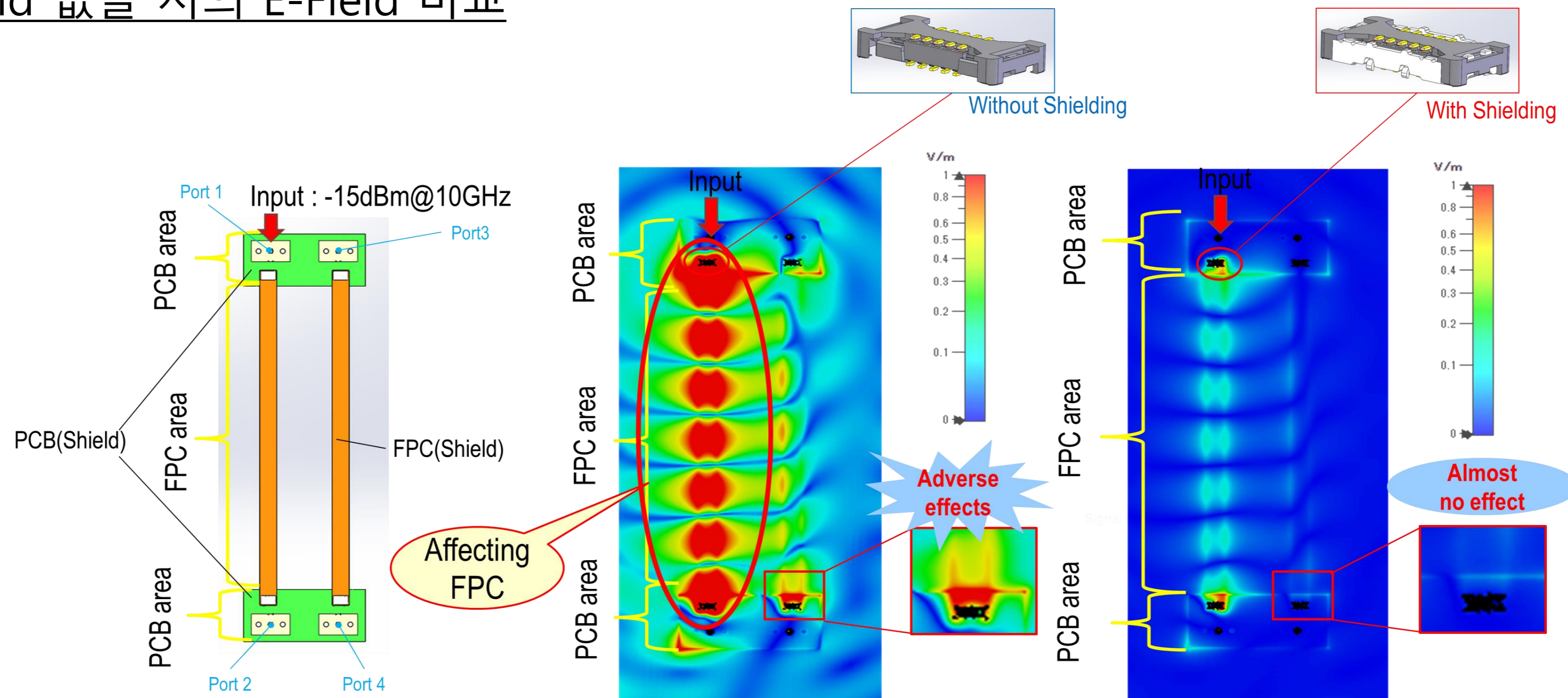
외부 노이즈의 영향을 받지 않는 신호 Line

◆ Pin assignment



▶ 5G 기기 특유의 EMI 문제를 풀 실드 디자인 설계(ZenShield®)로 저감

Shield 있을 시, Shield 없을 시의 E-Field 비교



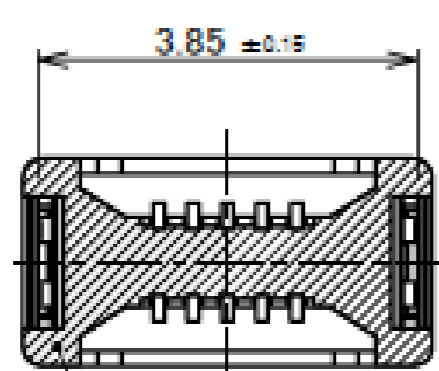
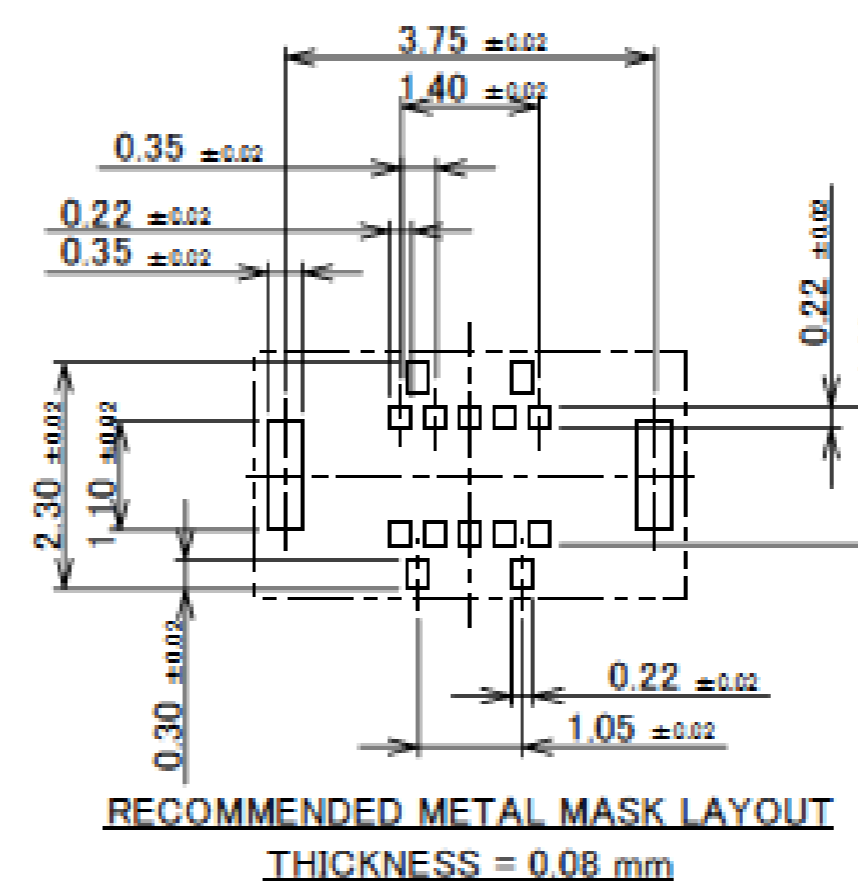
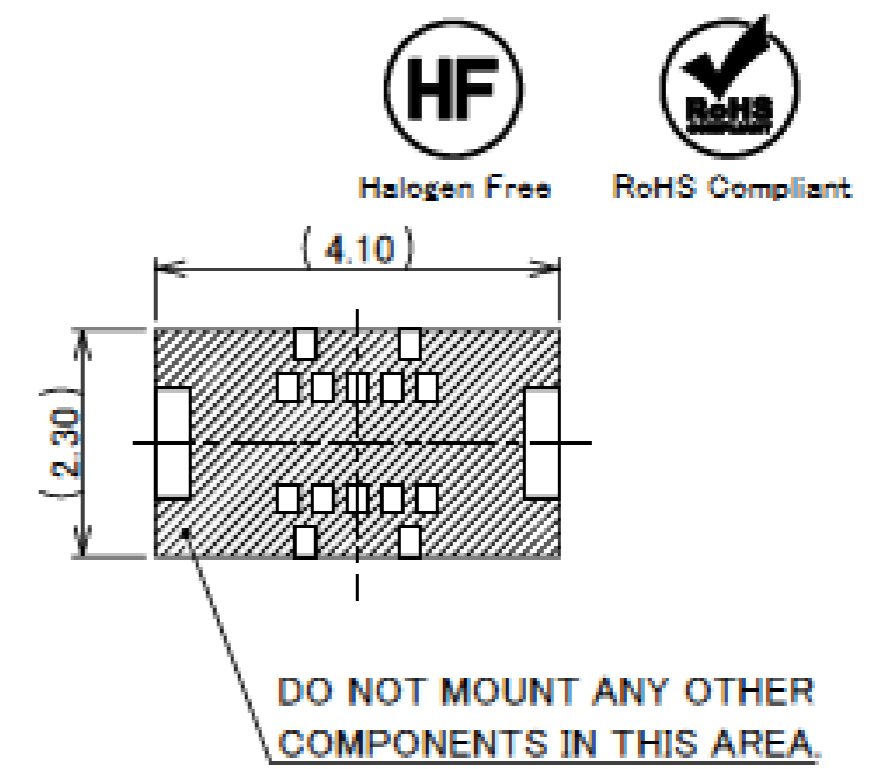
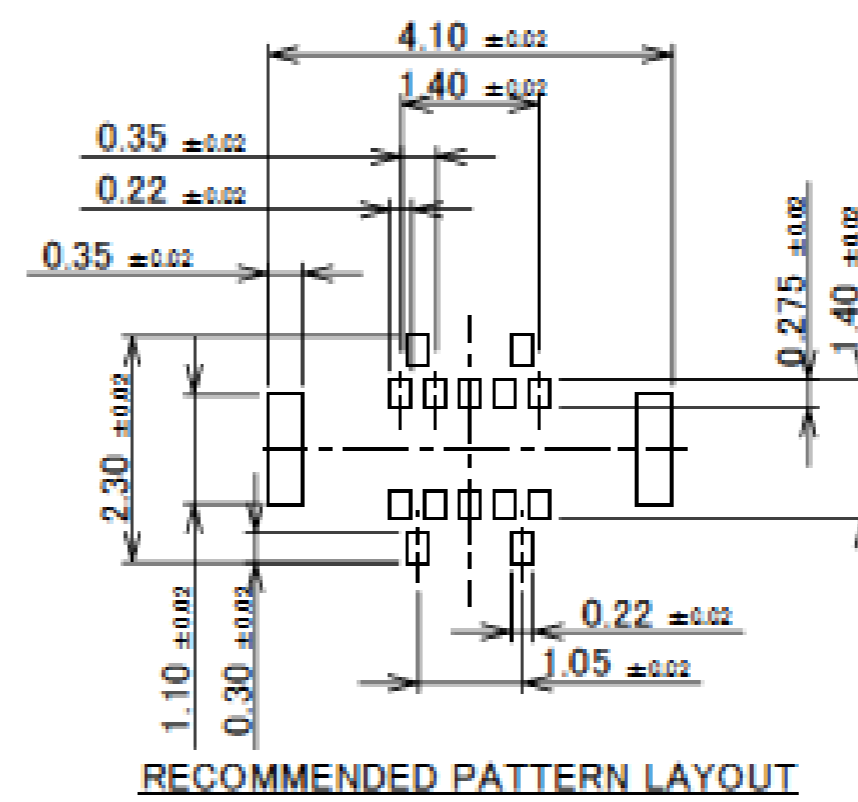
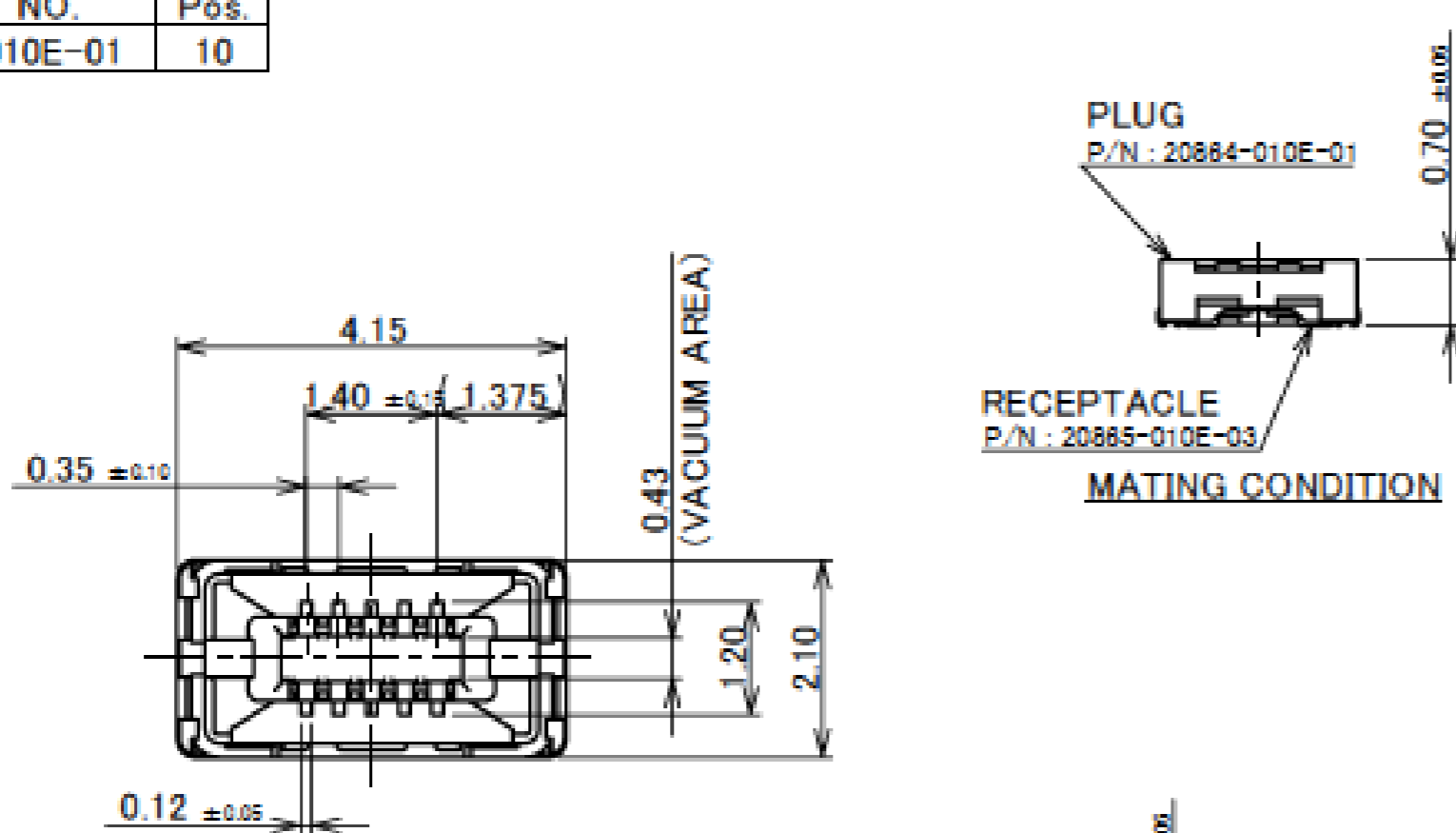
▶ 소형 · 저배의 제품 높이를 추구한 풀 실드 기판 대 기판 커넥터



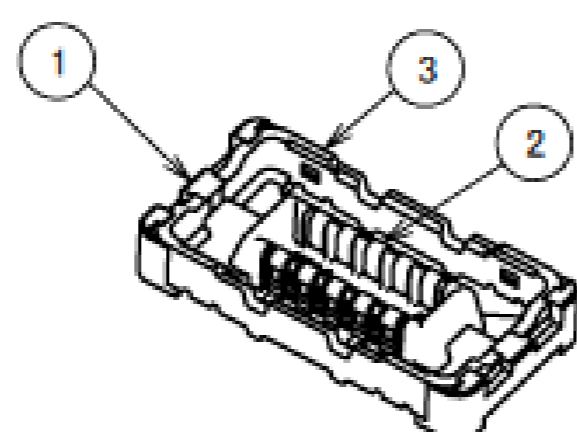
Component Parts Detail

Plug Assembly

Recommended P/N	20864-010E-01
PART NO.	Pos.
20864-010E-01	10



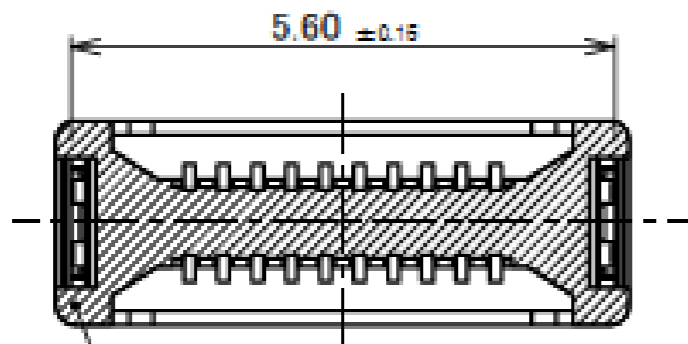
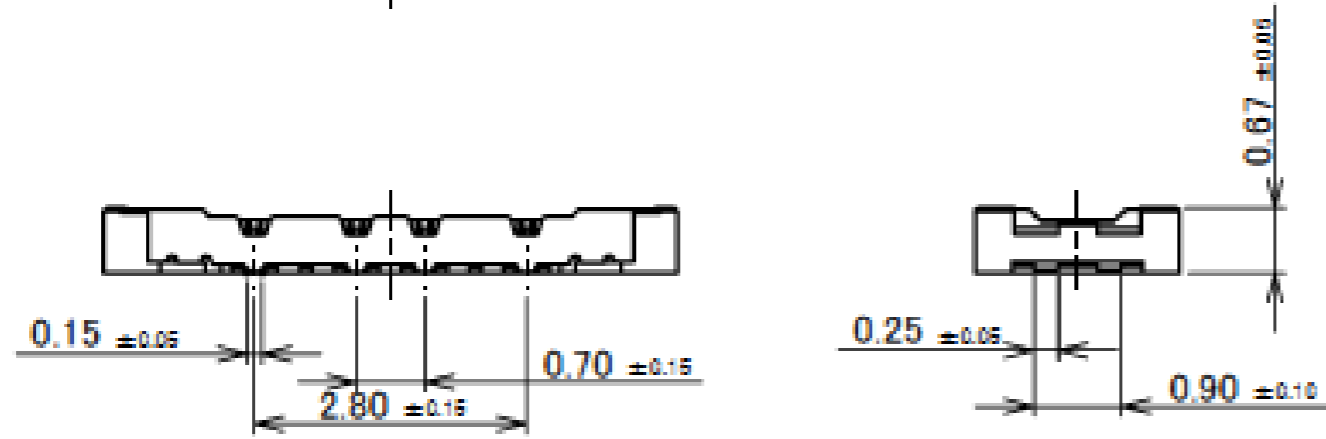
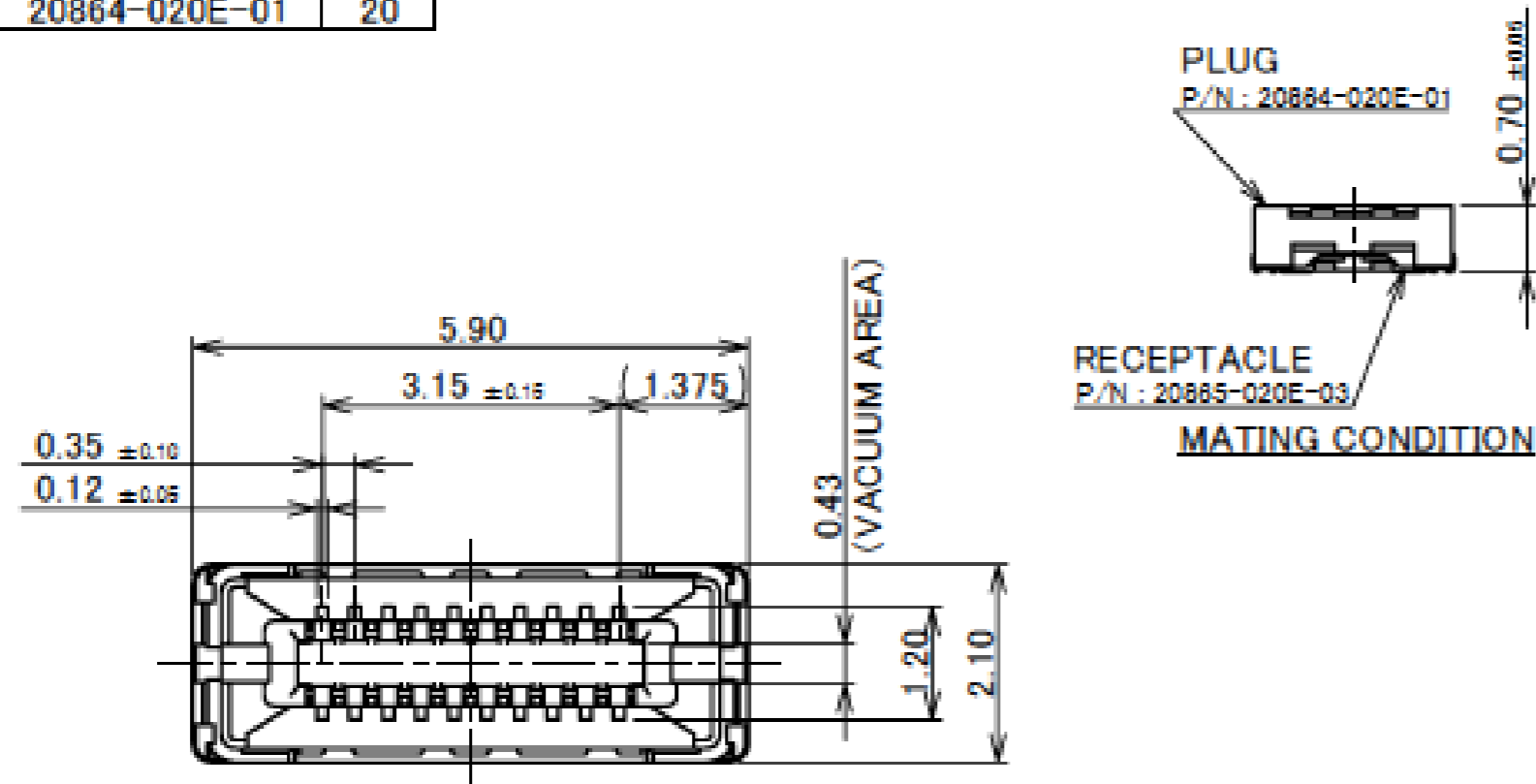
There is a possibility of dent shape in the bottom surface of HOUSING.



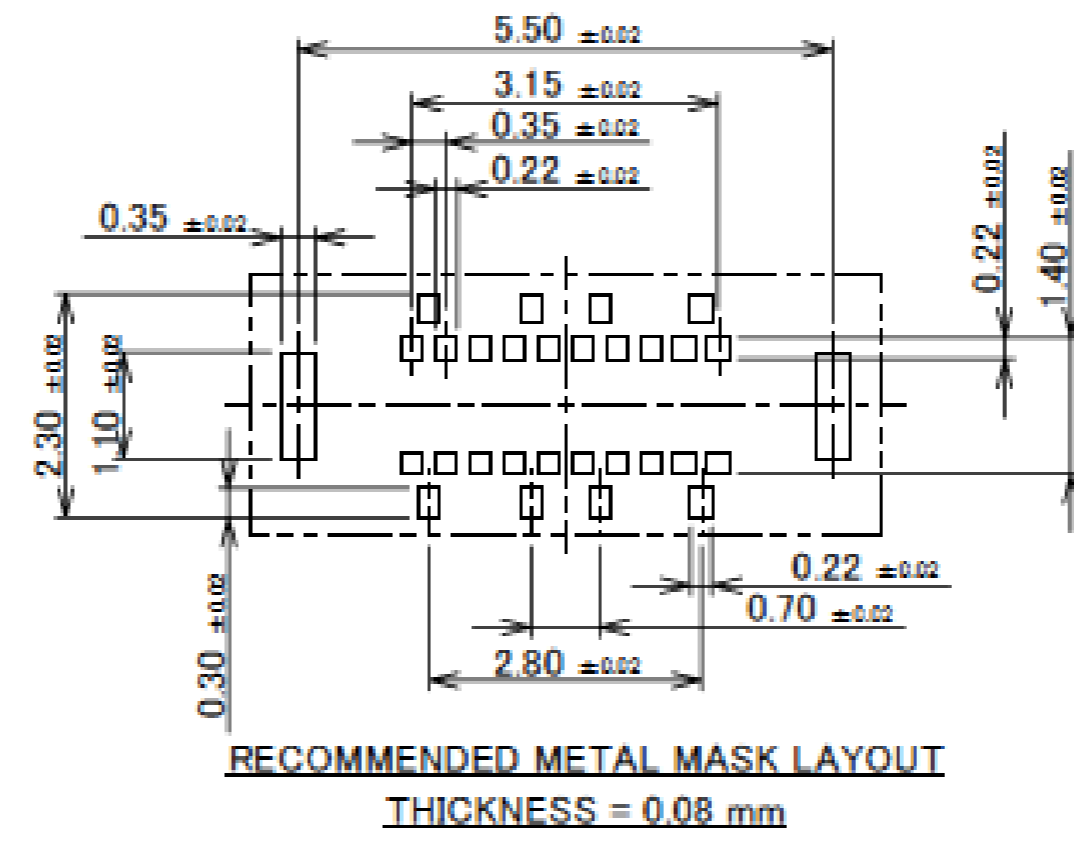
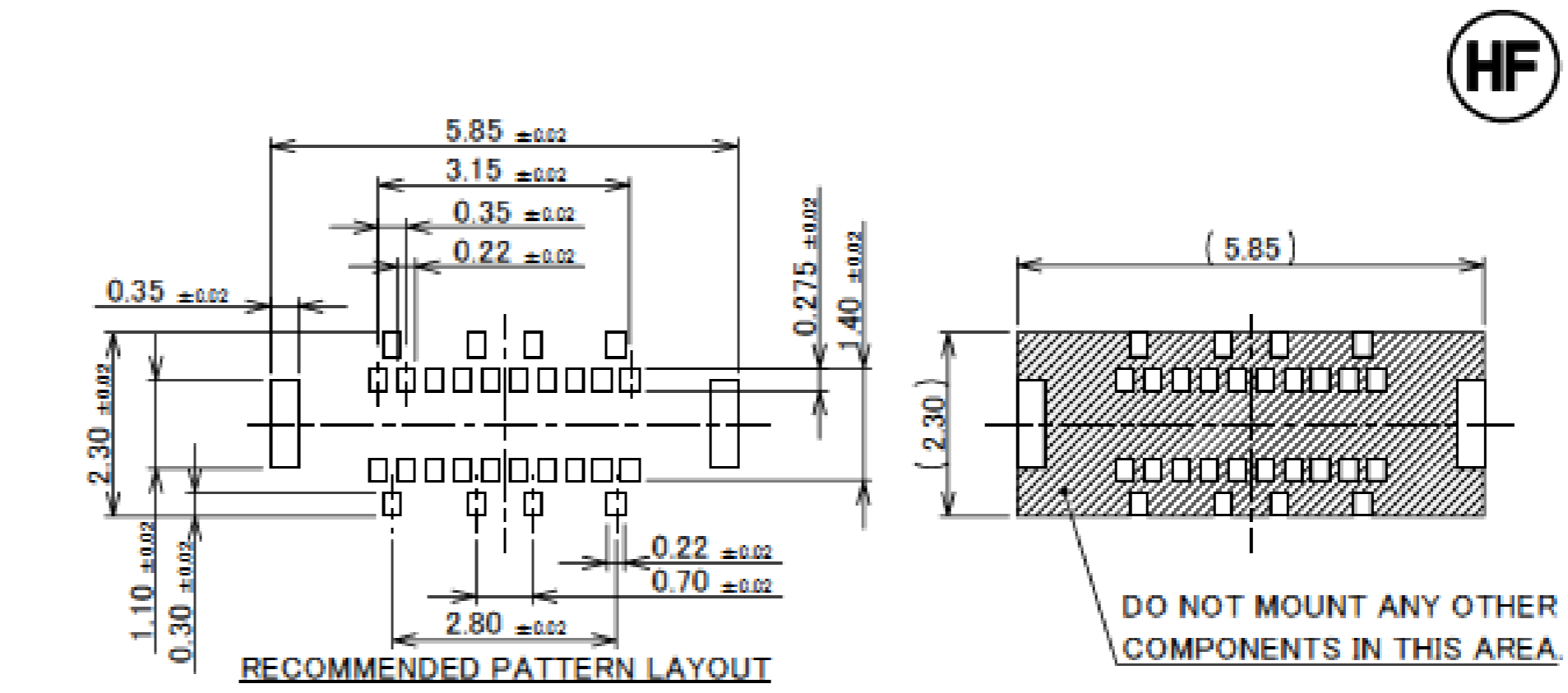
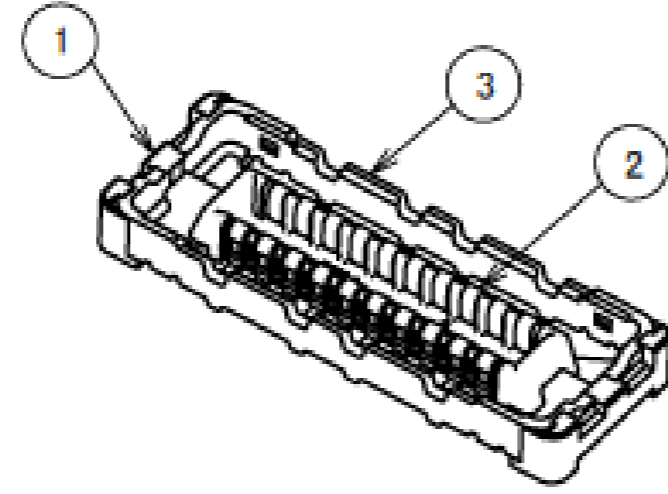
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0, BLACK

Plug Assembly

Recommended P/N		20864-020E-01
PART NO.	Pos.	
20864-020E-01	20	



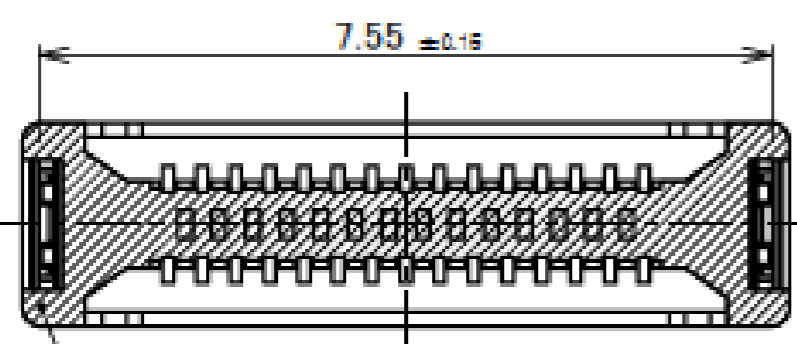
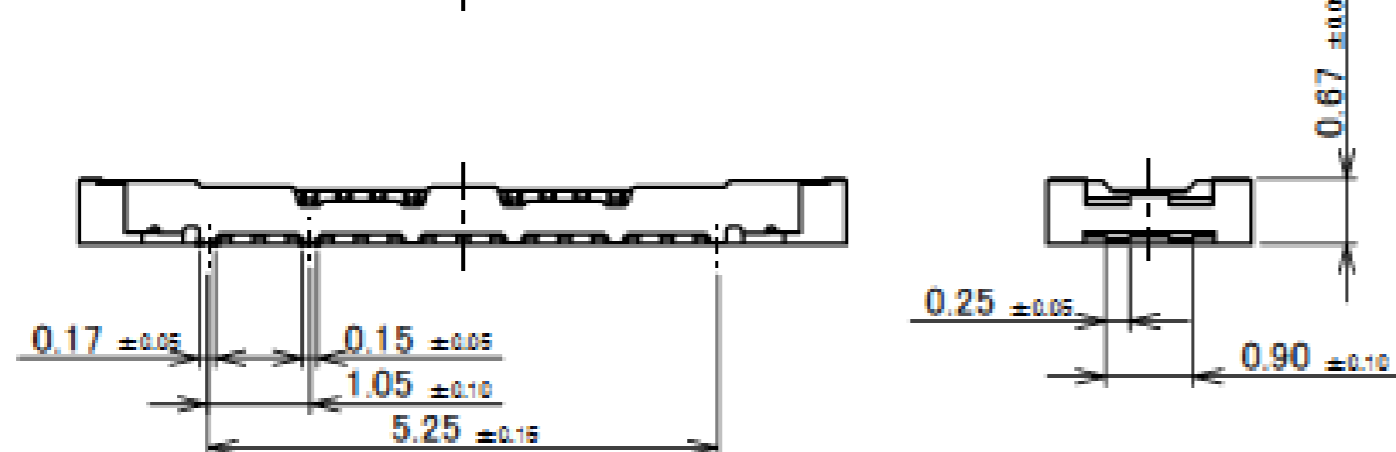
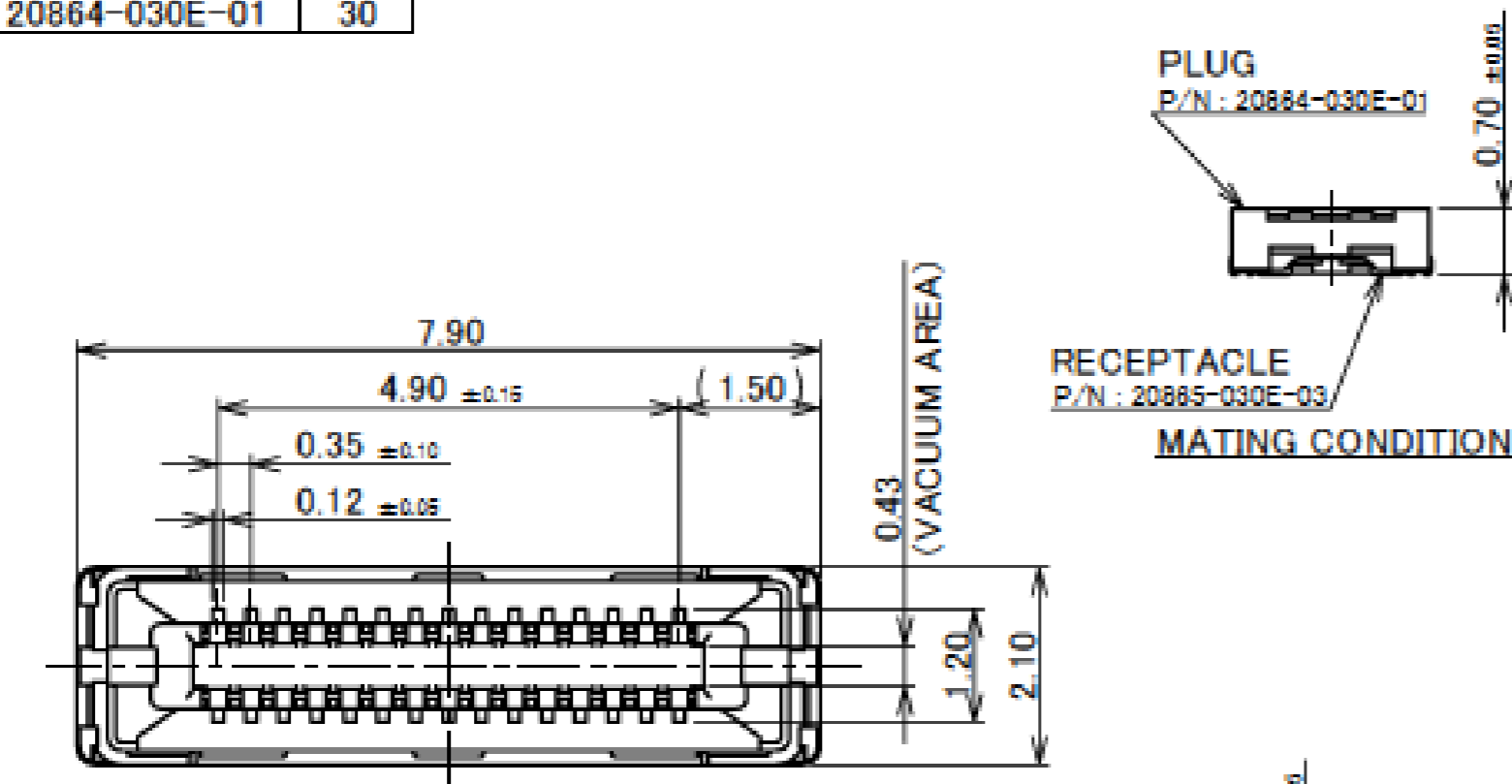
There is a possibility of dent shape in the bottom surface of HOUSING.



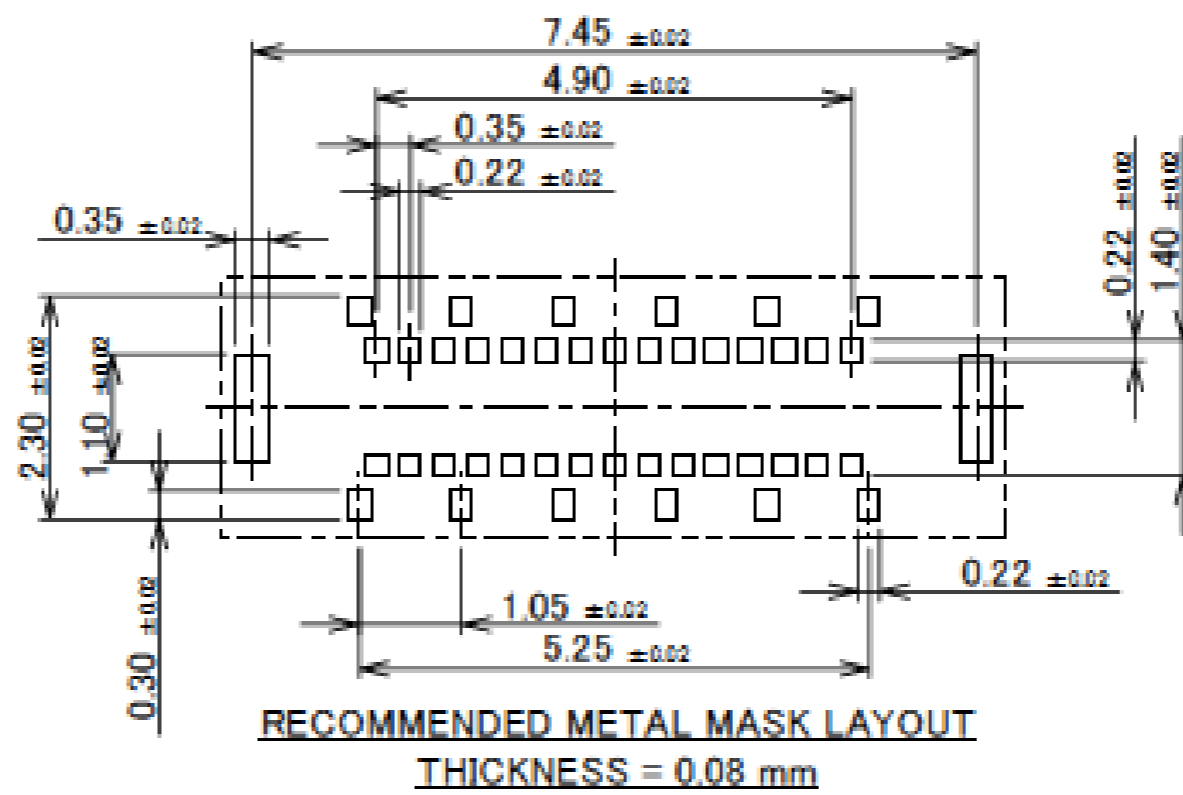
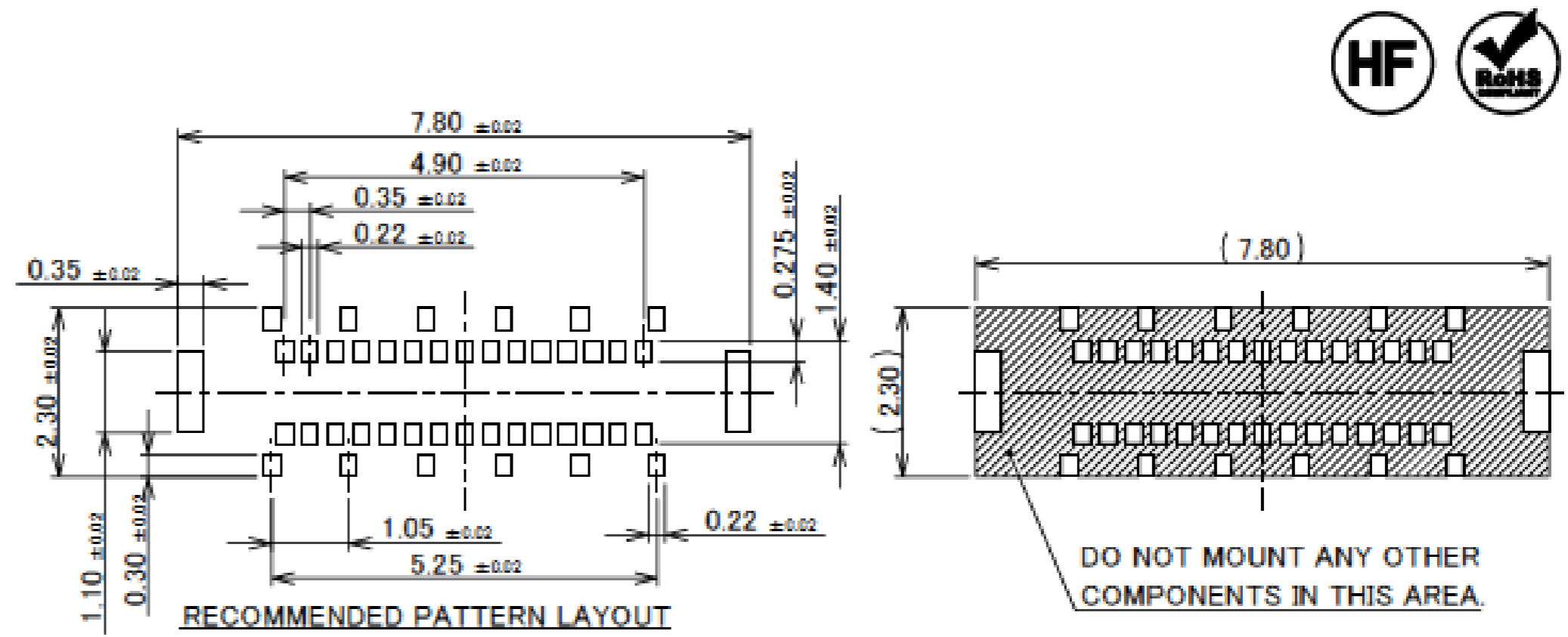
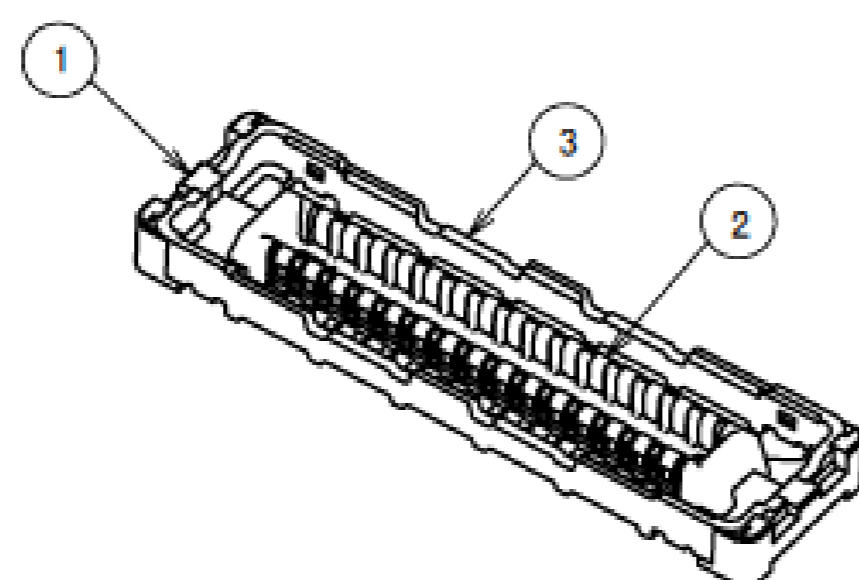
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

Rev.9

Recommended P/N		20864-030E-01
PART NO.	Pos.	
20864-030E-01	30	



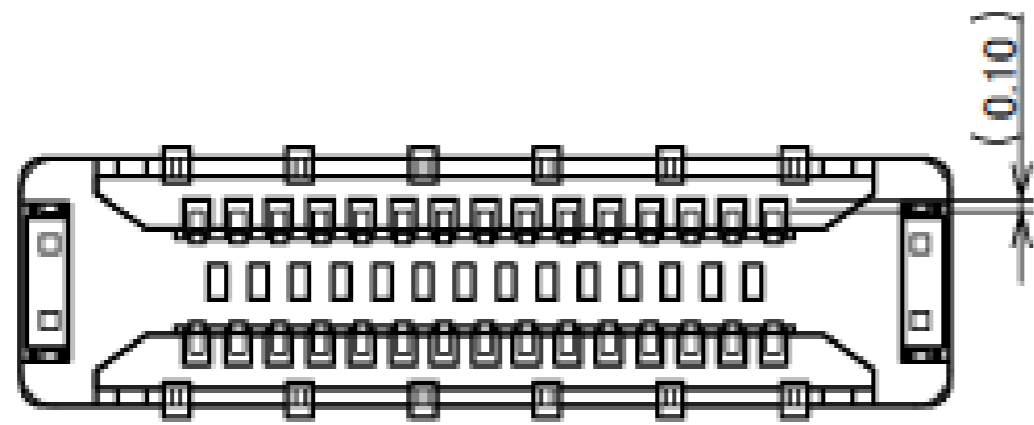
There is a possibility of dent shape in the bottom surface of HOUSING.



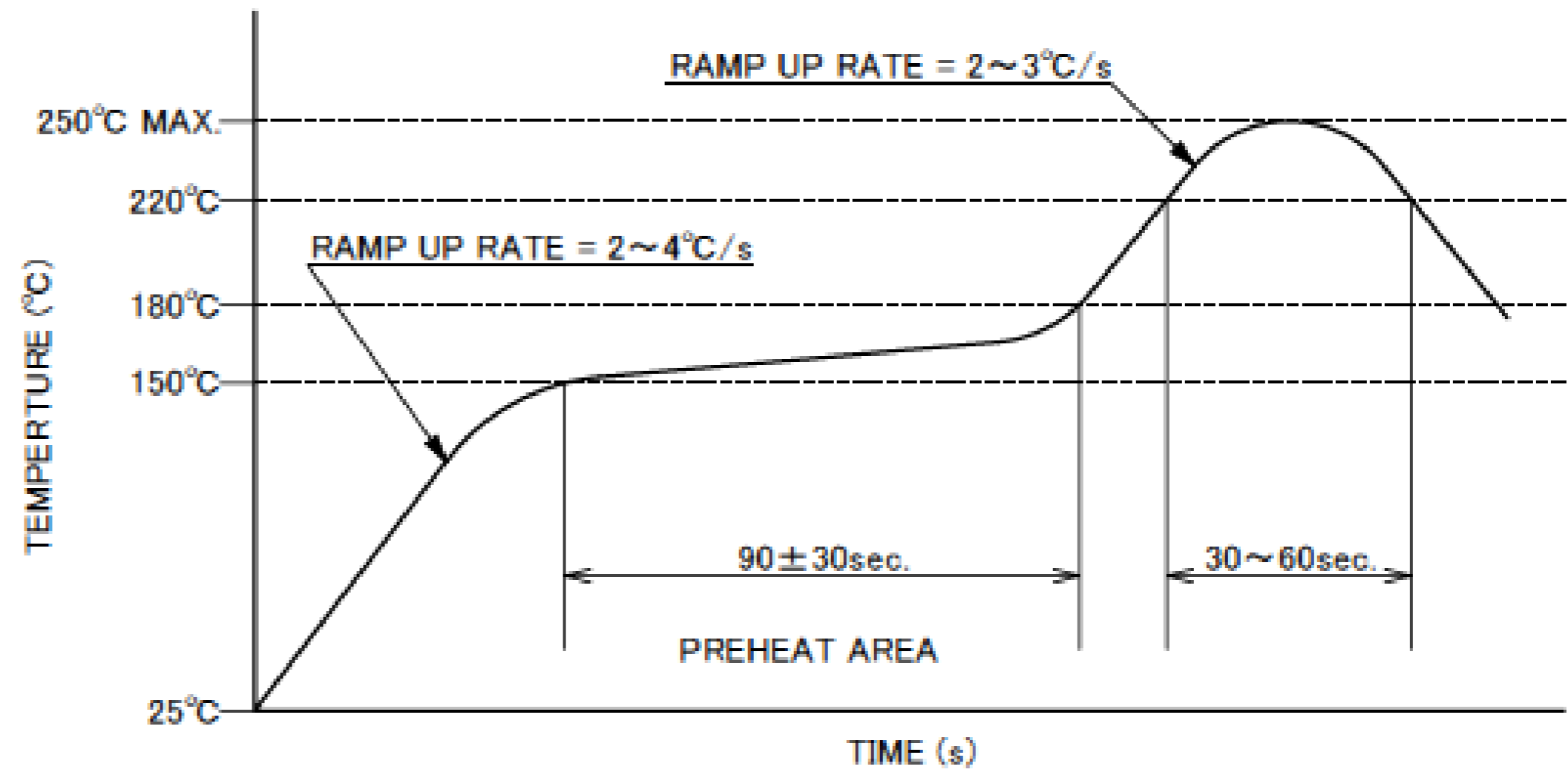
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

Rev.9

Plug Assembly



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

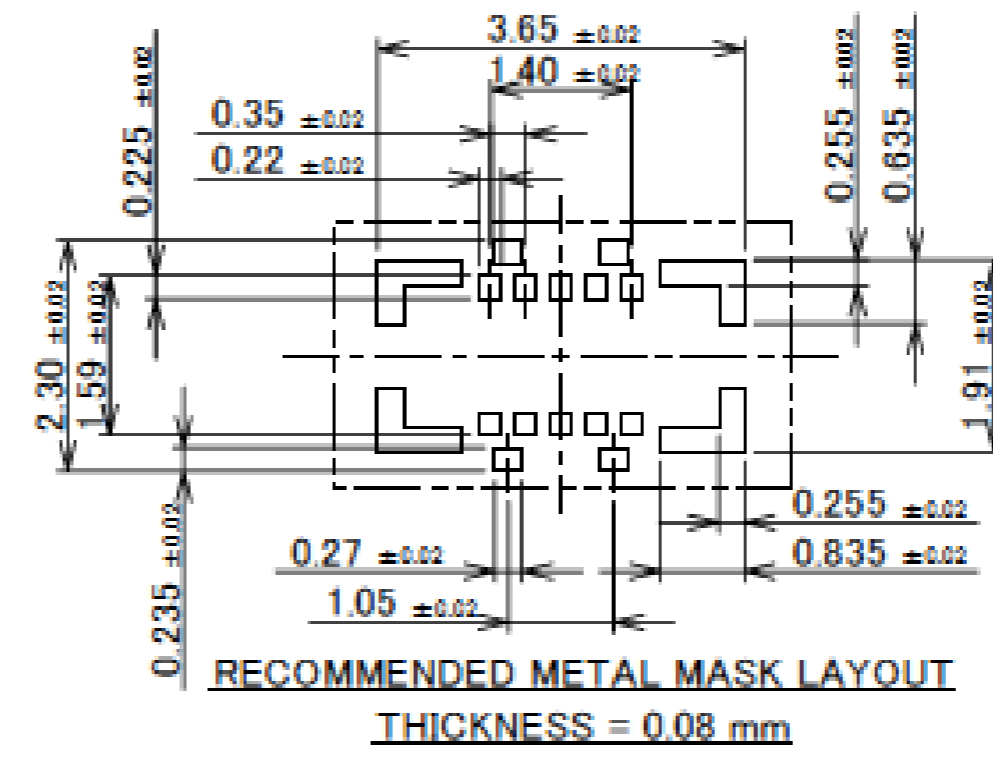
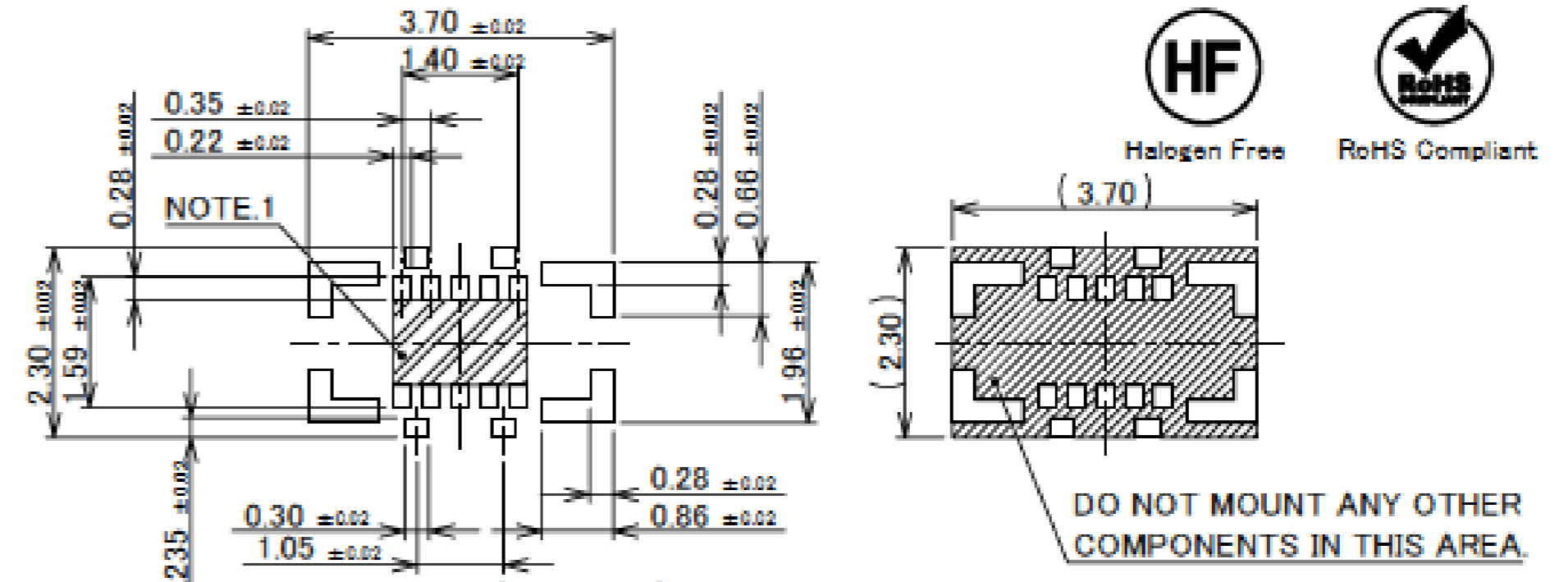
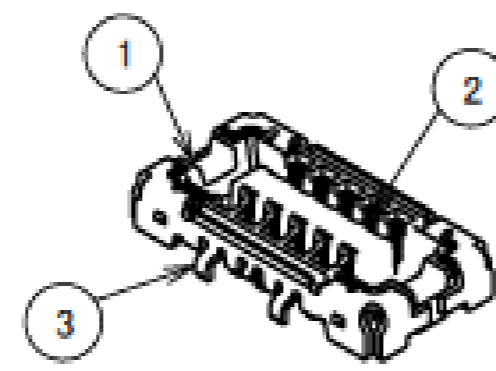
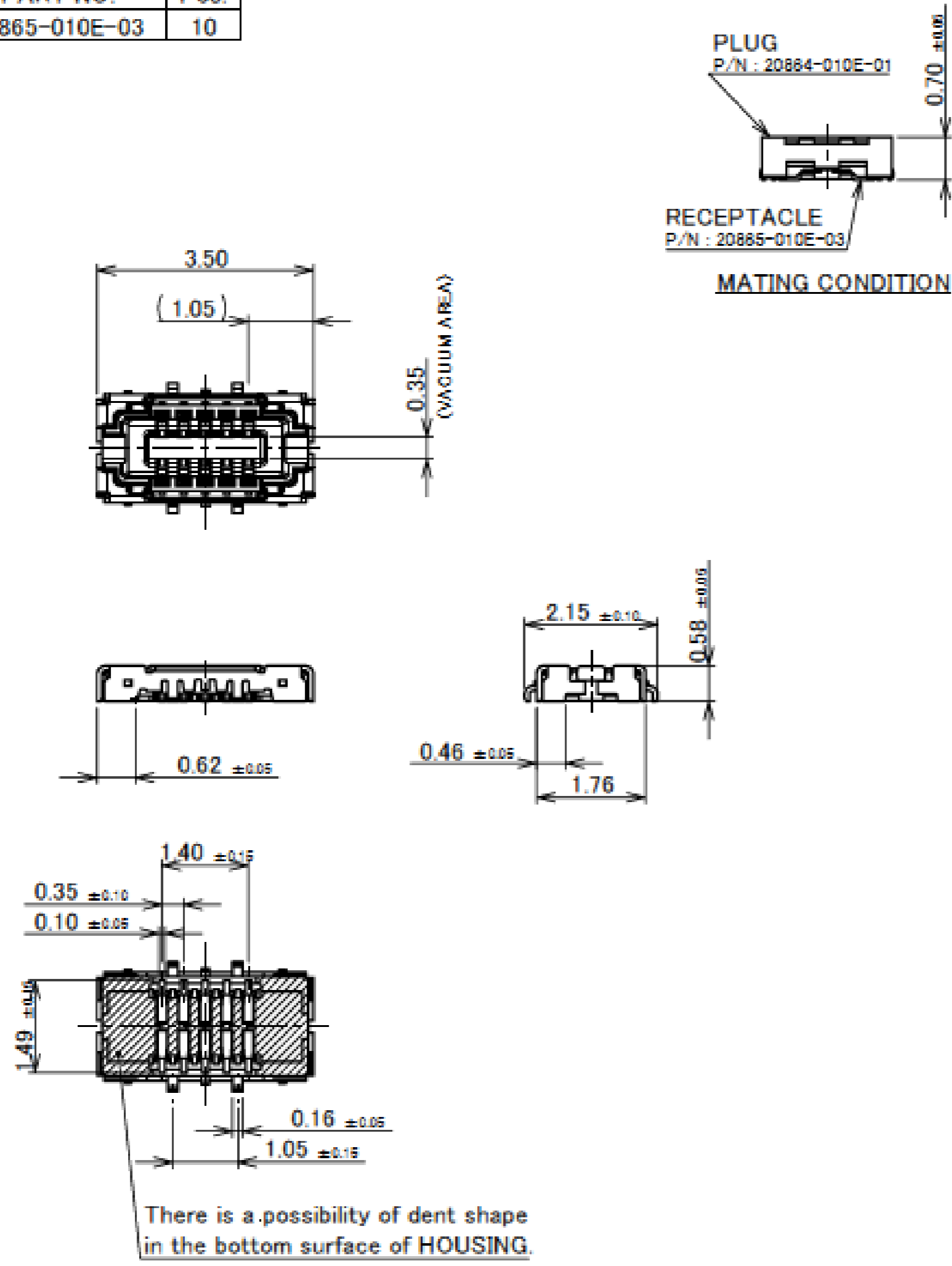
Rev.9

ITEMS	SPECIFICATION
APPLICABLE CONNECTOR PART No.	20865-0**E-**
RATING VOLTAGE	60V AC(r.m.s) / DC (PER CONTACT PIN)
RATING AMPERAGE (FOR SIGNAL CONTACT)	10P:1.0 A MAX. AC/DC x PIN COUNTS = 10.0 A (TOTAL) 12P AND OVER : 12.0 A AC/DC (TOTAL)
OPERATING TEMPERATURE	233~358K(-40°C~85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENDING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 40mohm MAX. / AFTER TEST : \triangleleft40mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : \triangleleft20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1,000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	10 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 2.0N/Pin MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10 CYCLES 0.15N/Pin MIN.
COPLANARITY	0.08 MAX
PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18022
INSTRUCTION MANUAL	HIM-18019
APPEARANCE CRITERIA No.	QLS-A***

Rev.9

Receptacle Assembly

Recommended P/N		20865-010E-03
PART NO.	Pos.	
20865-010E-03	10	

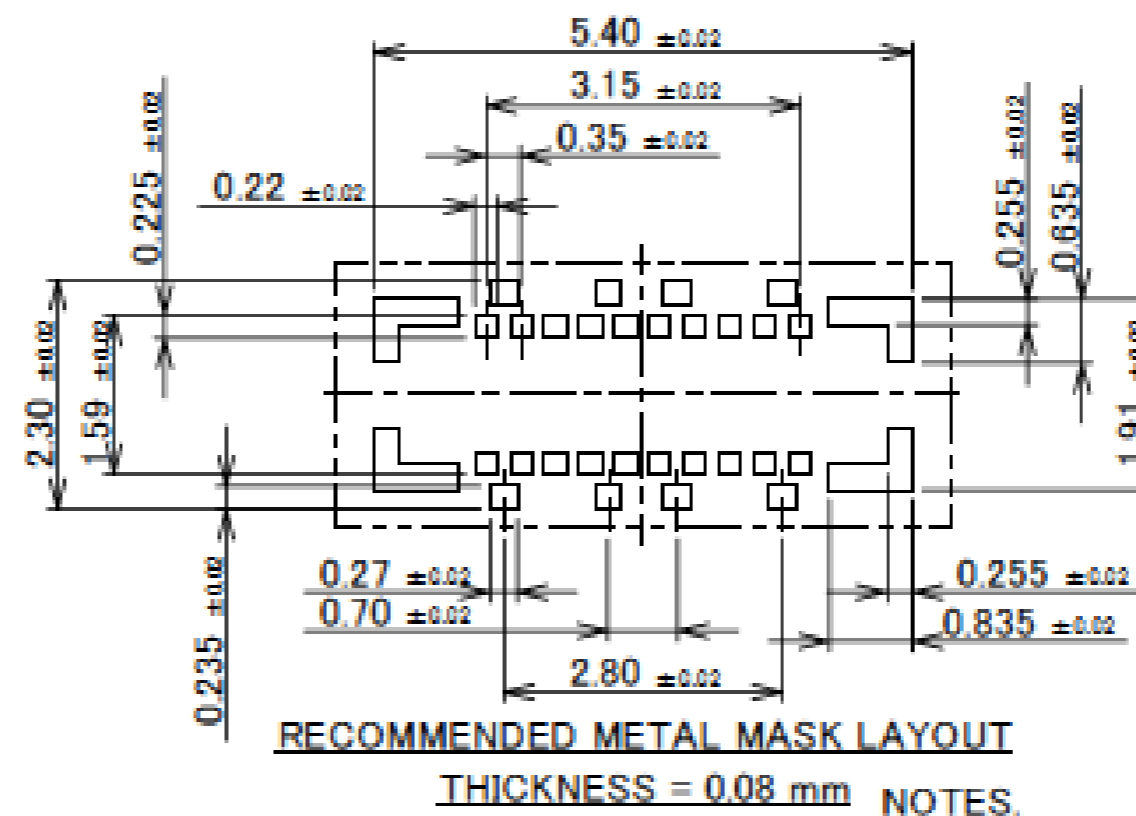
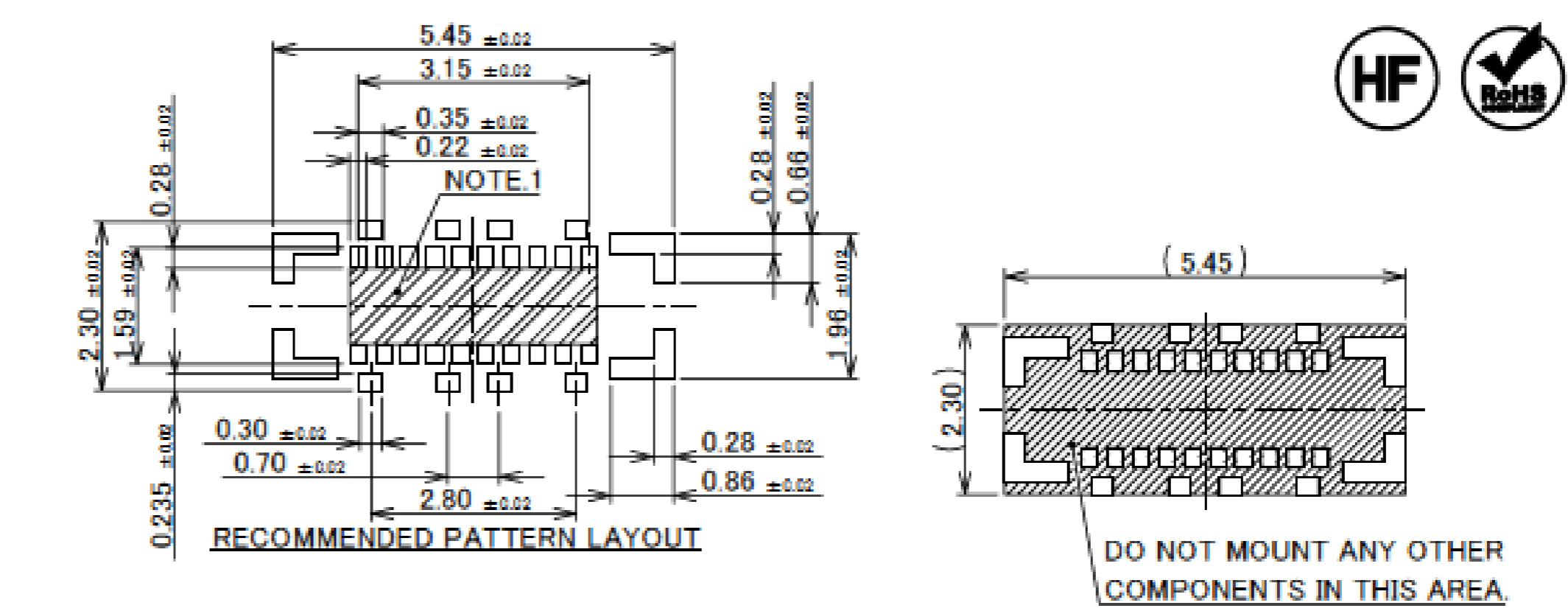
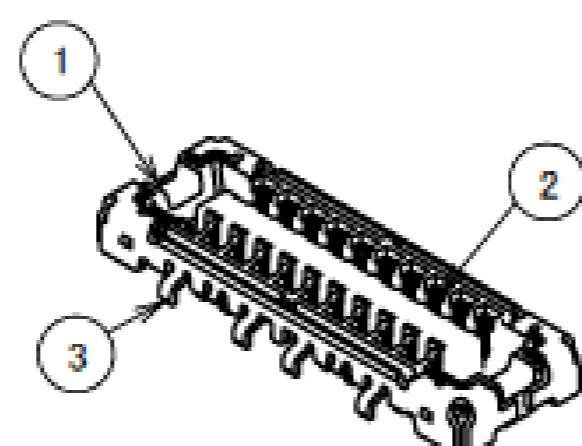
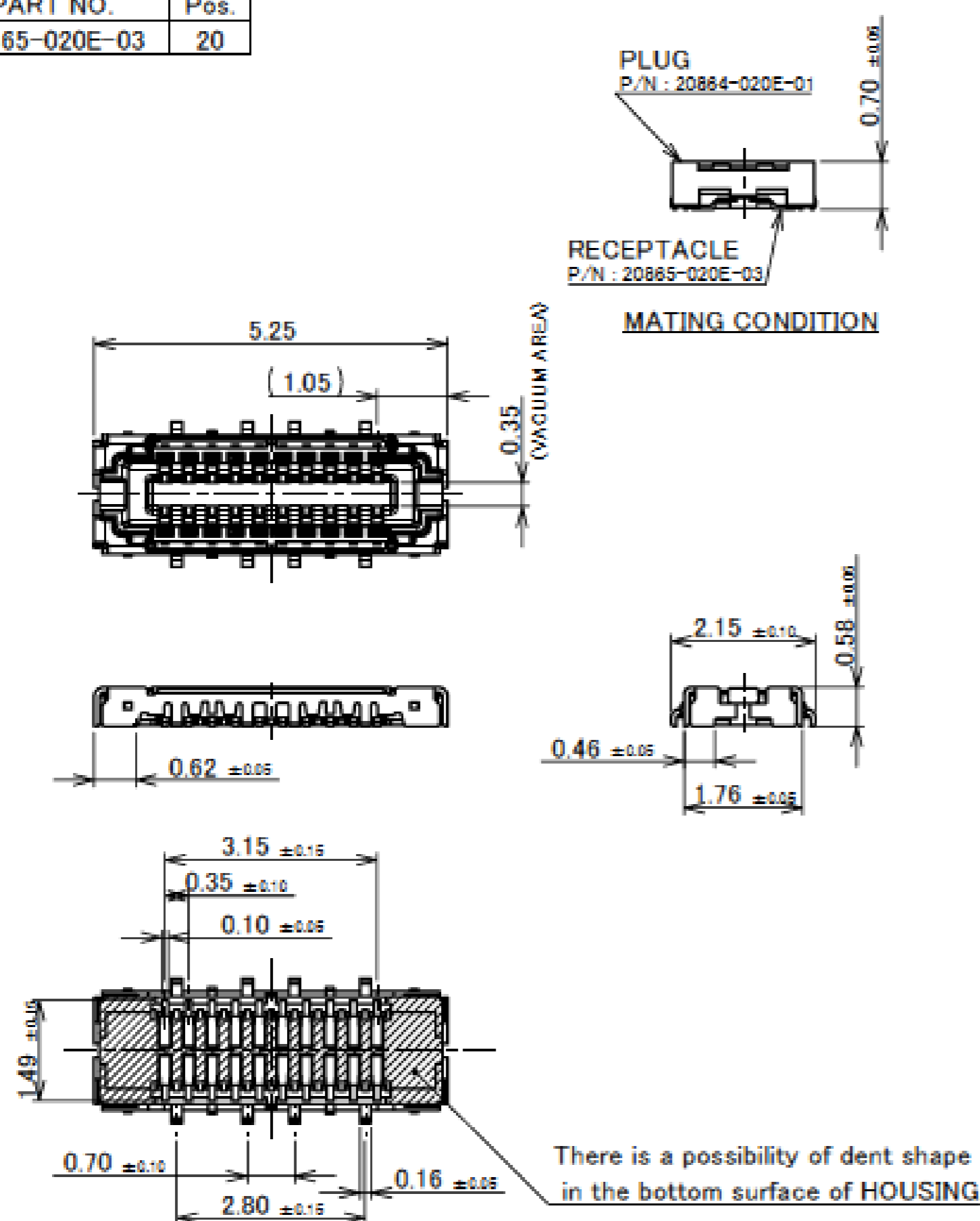


NOTES.
1. FOOT PRINT PATTERN PROHIBITION AREA :
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
IF SURFACE TRACES ARE ROUNDED.

NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0 BLACK

Rev.9

Recommended P/N		20865-020E-03
PART NO.	Pos.	
20865-020E-03	20	



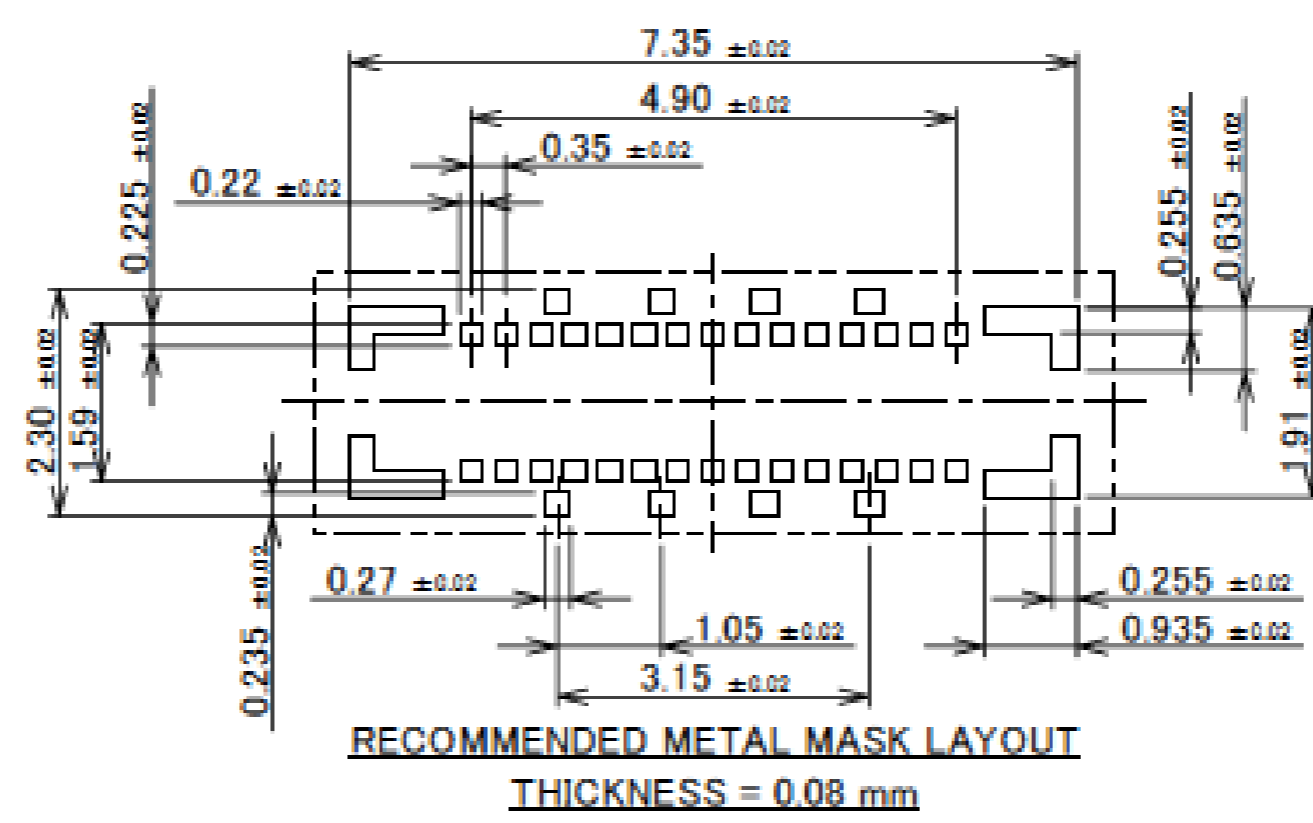
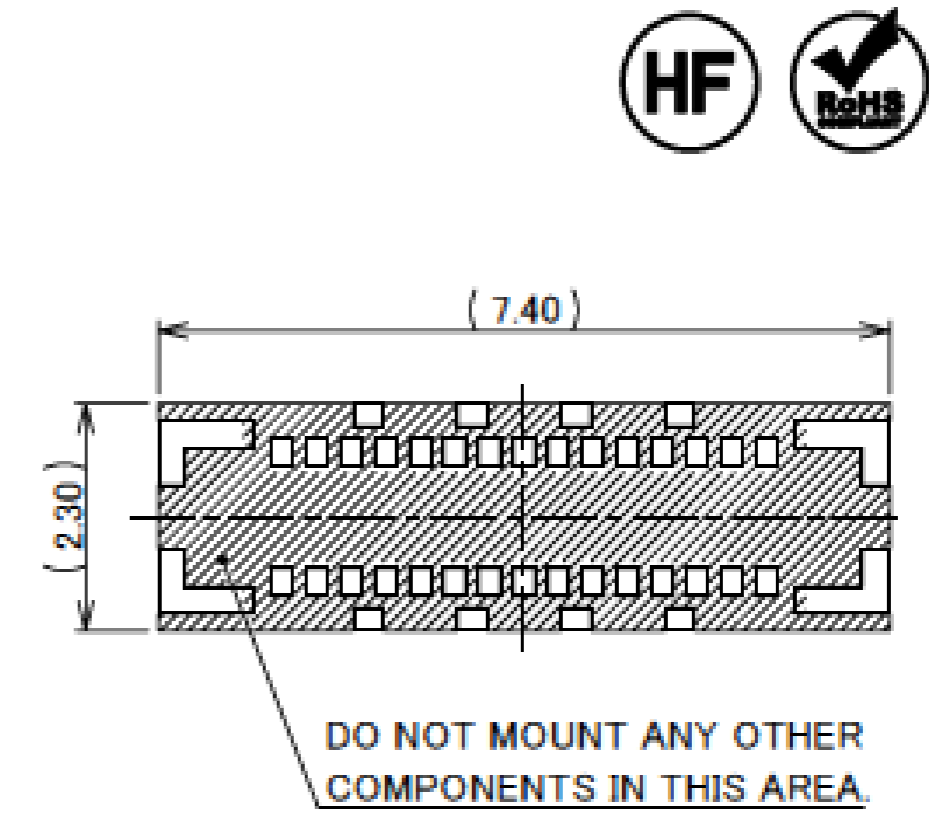
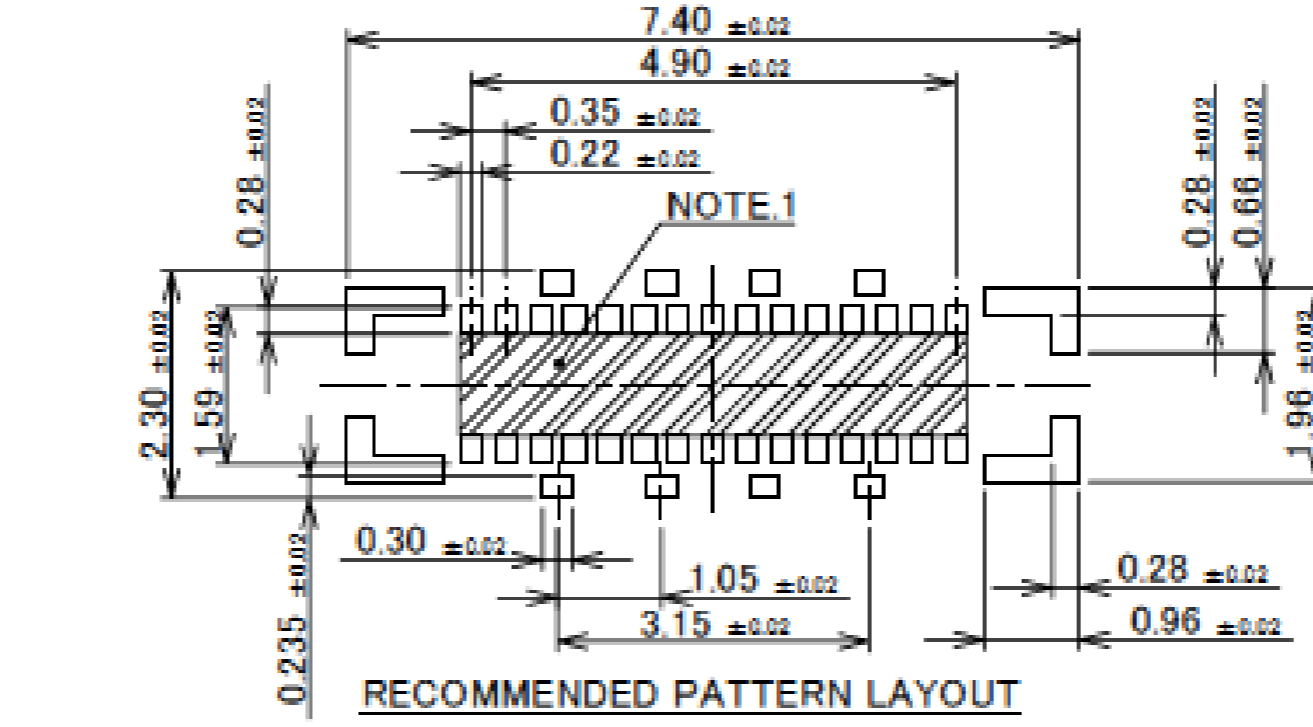
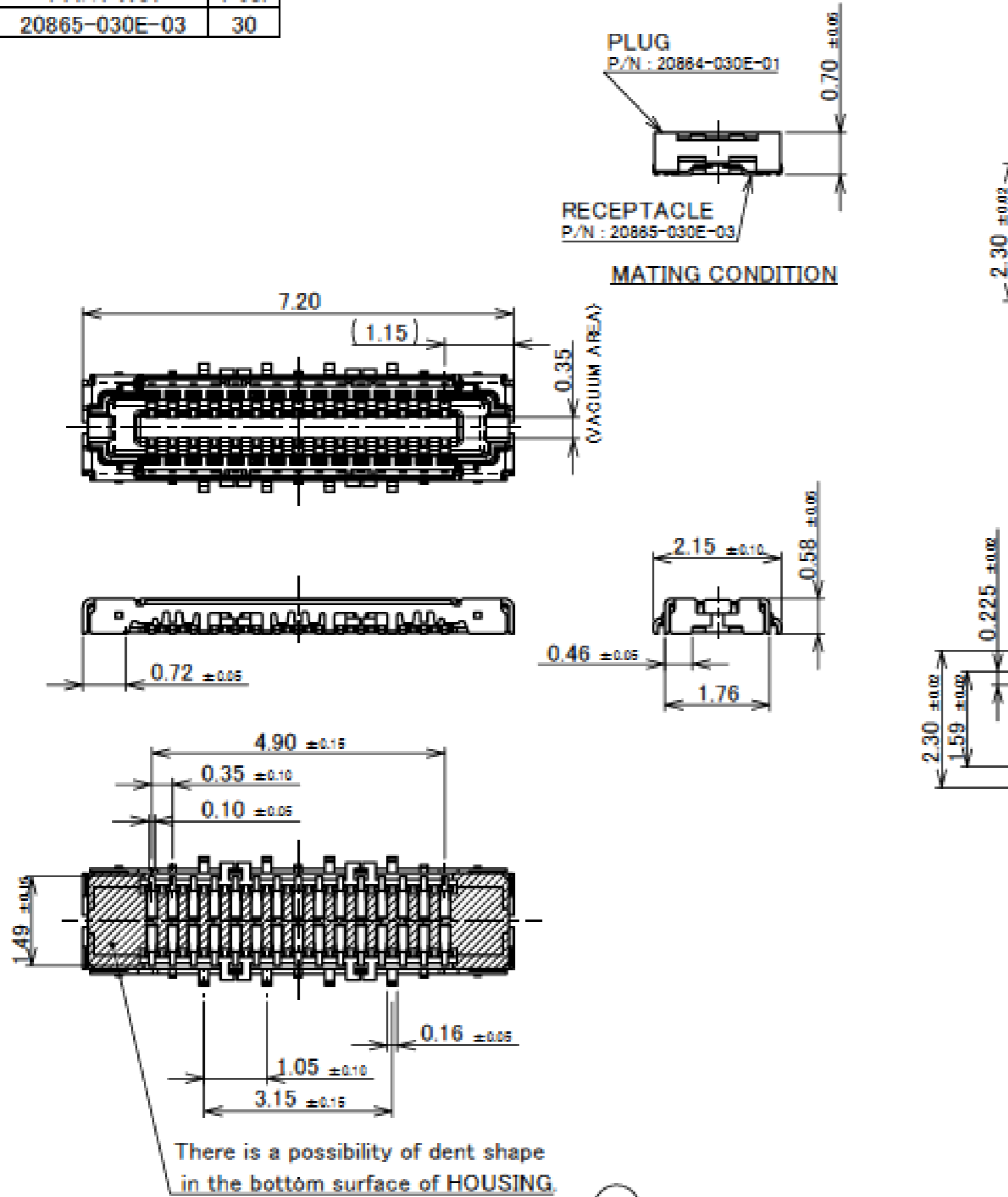
NOTES.
1. FOOT PRINT PATTERN PROHIBITION AREA :
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
IF SURFACE TRACES ARE ROUNDED.

NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0 BLACK

Rev.9

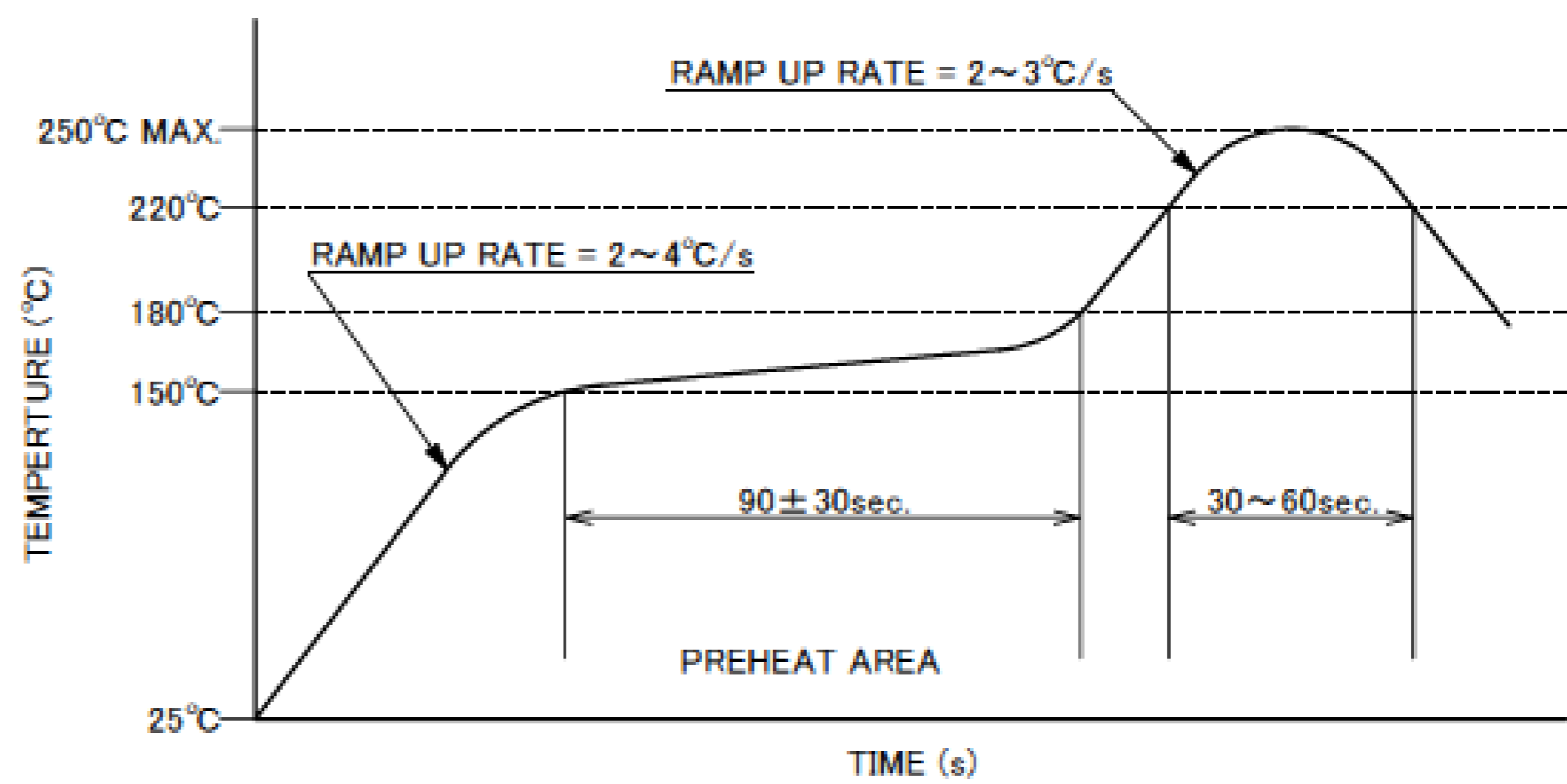
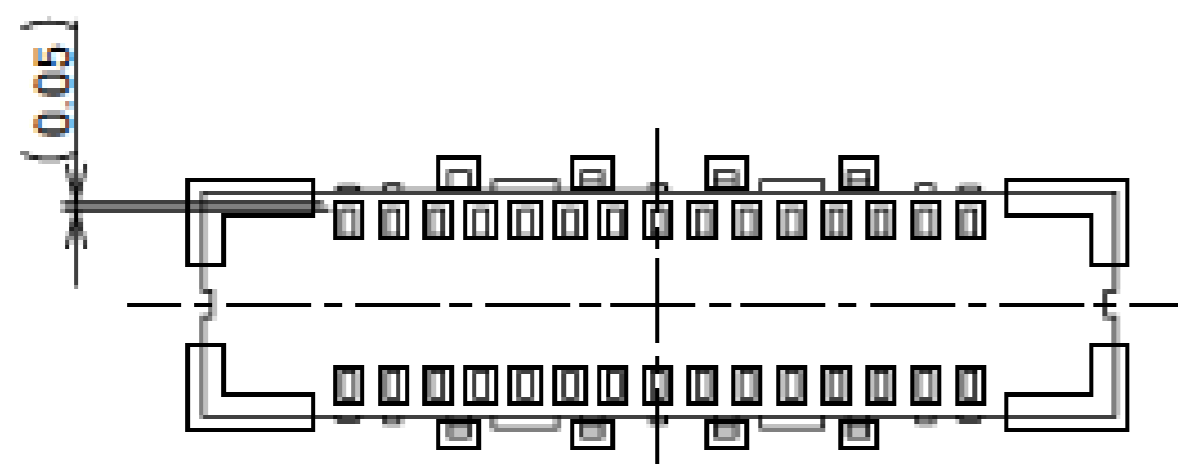
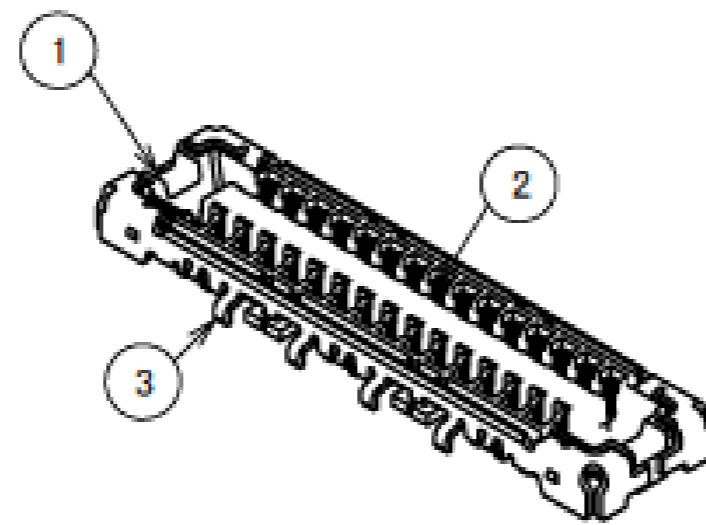
Receptacle Assembly

Recommended P/N		20865-030E-03
PART NO.	Pos.	
20865-030E-03	30	



NOTES
1. FOOT PRINT PATTERN PROHIBITION AREA :
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
IF SURFACE TRACES ARE ROUNDED.

3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0 BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.9

Receptacle Assembly

ITEMS	SPECIFICATION
APPLICABLE CONNECTOR PART No.	20864-0**E-**
RATING VOLTAGE	60V AC(r.m.s) / DC (PER CONTACT PIN)
RATING AMPERAGE (FOR SIGNAL CONTACT)	10P:1.0 A MAX. AC/DC x PIN COUNTS = 10.0 A (TOTAL) 12P AND OVER : 12.0 A AC/DC (TOTAL)
OPERATING TEMPERATURE	233~358K(-40°C~85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENDING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 40mohm MAX. / AFTER TEST : Δ 40mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : Δ 20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1,000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	10 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 2.0N/Pin MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10 CYCLES 0.15N/Pin MIN.
COPLANARITY	0.08 MAX.
PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18023
INSTRUCTION MANUAL	HIM-18019
APPEARANCE CRITERIA No.	QLS-A***

Rev.9

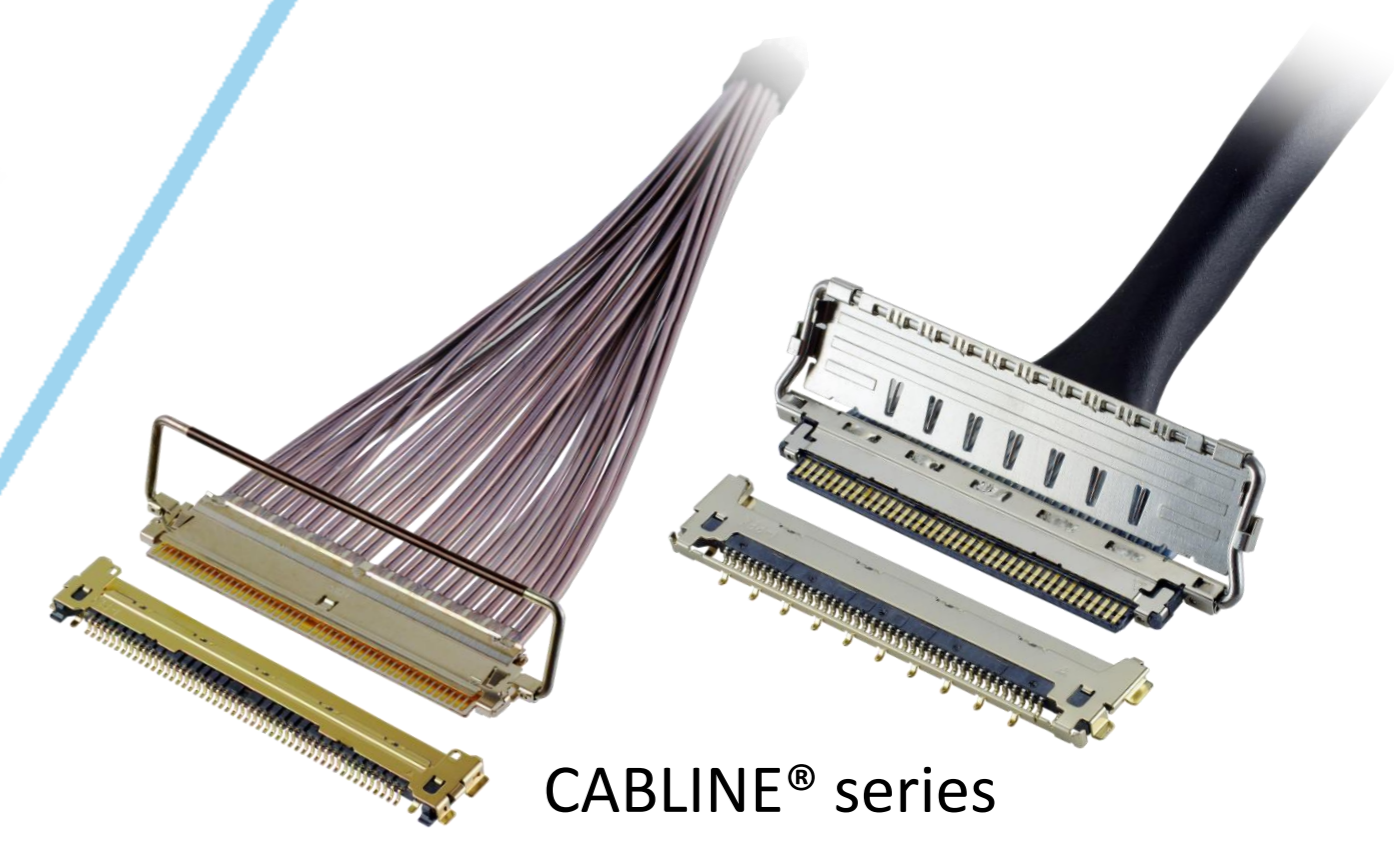
Custom Connectors Available

 RF Connector

MHF® series



Micro-coaxial/Twinax/
Discrete Wire Connector



CABLINE® series



Optical Module

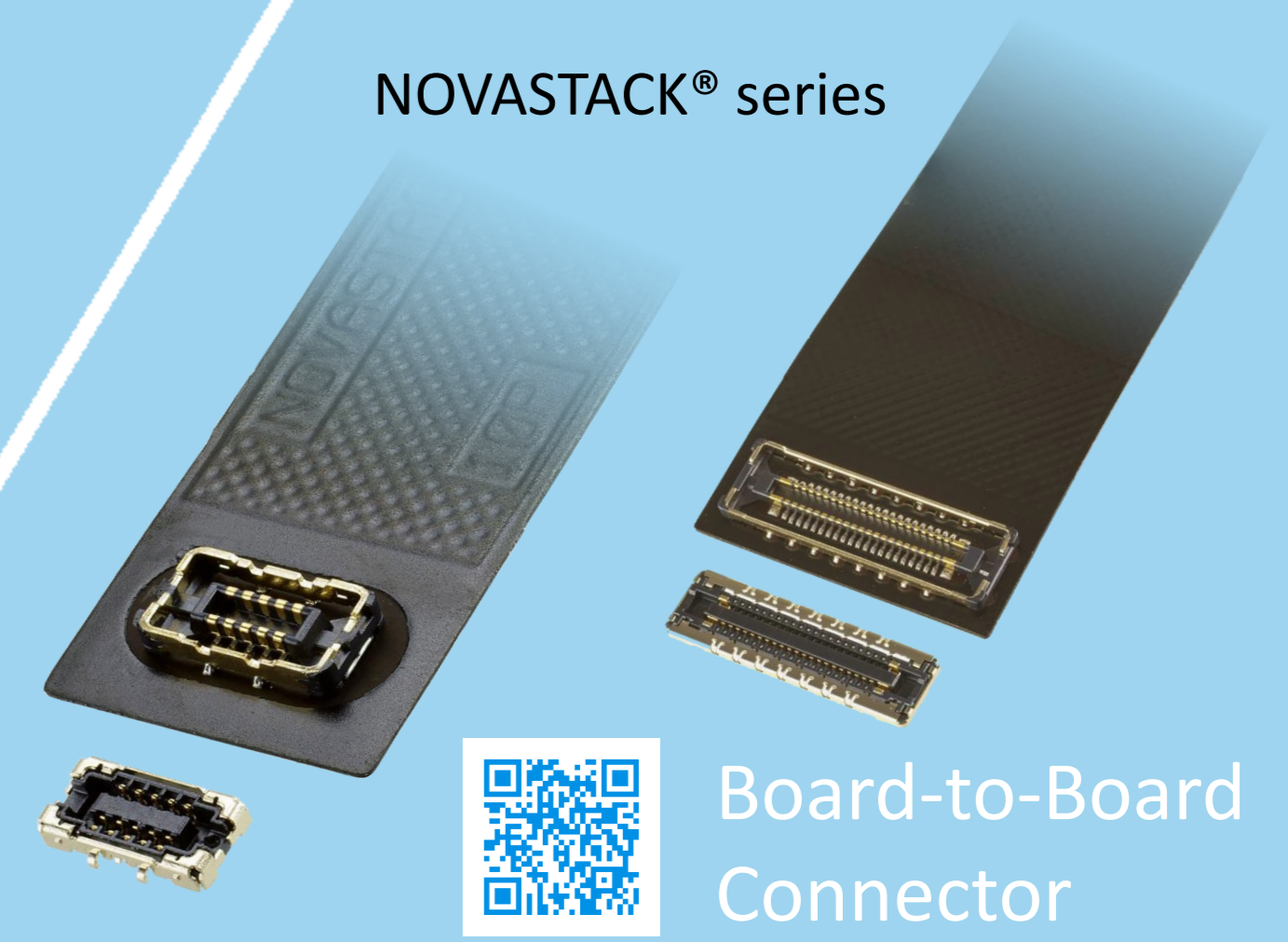
LIGHTPASS® series



NOVASTACK® series



Board-to-Board Connector



Power Connector/
Terminal

AP series

ISH® series



MINIFLEX® series

EVAFLEX® series



FPC FFC Connector



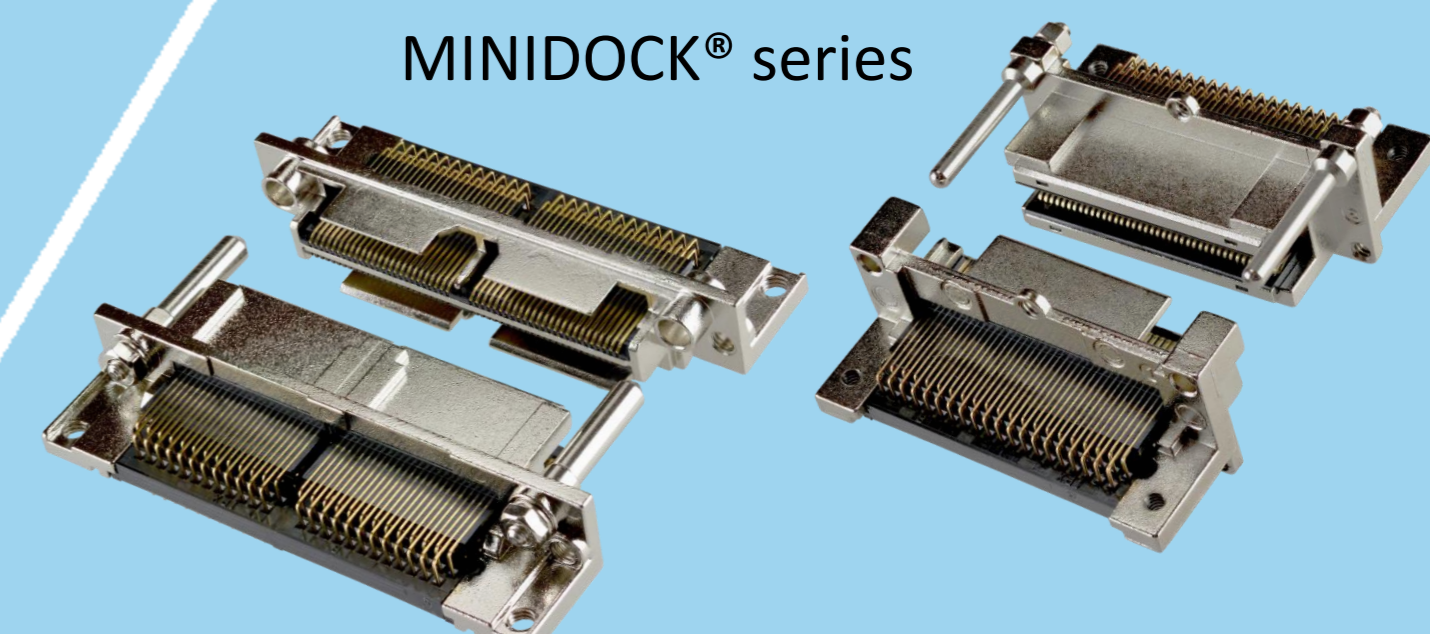
Inquiry



MINIDOCK® series



I/O Connector



I-PEX, MHF, CABLINE, LIGHTPASS, NOVASTACK, ISH, IARPB, MINIFLEX, EVAFLEX, MINIDOCKS and ZenShield are registered trademarks of I-PEX Inc. Please note that the contents in the catalog might be changed without prior notification. I-PEX Inc. assumes no responsibility for any inaccuracies or obligation to update information on these documents. Please be sure to read and understand the latest "Precautions for Use" and "Instruction Manual" before you use our products. We shall not be responsible for any defects, damages or troubles in case you use our products without following the precautions for use. Please feel free to contact our sales representatives when you use our products for any applications that require very high reliability and safety, or that relate to human life (ex. nuclear power control, aerospace, transportation, medical equipment, safety equipment etc.).

Contact your sales representative or more detailed information.

www.i-pex.com



I-PEX

© I-PEX Inc. 2024
All rights reserved